

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-16. (canceled)

17. (previously presented) A shielded cable comprising:  
a cable body comprising electrical conductors disposed within an insulating substrate;  
a vacuum metallized shielding layer disposed over the insulating substrate;  
a metallized thermoform connector coupled to an end portion of the cable body and electrically coupled to the vacuum metallized layer, wherein the connector can be electrically coupled to a grounded housing so as to ground the shielding layer and connector; and  
wherein the connector further comprises spaced protrusions, wherein the connector is electrically coupled to the metallized layer with the spaced protrusions, and  
wherein the spaced protrusions have a height and spacing between an adjacent protrusion that is no larger than one-half a wavelength of a released radiation.

18-40. (canceled)

41. (previously presented) The cable of claim 17 further comprising an insulating top coating disposed over the vacuum metallized layer to insulate the vacuum metallized layer.

42. (previously presented) The cable of claim 41 wherein the insulating top layer extends to a point short of the connector such that the connector is electrically coupled to the metallized layer.

43. (previously presented) The cable of claim 17 wherein the vacuum metallized layer has a thickness between approximately one-half micron to twelve microns.

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44. (previously presented) The cable of claim 17 wherein the metallized thermoform is coupled to an outside surface of a nonconductive connector.